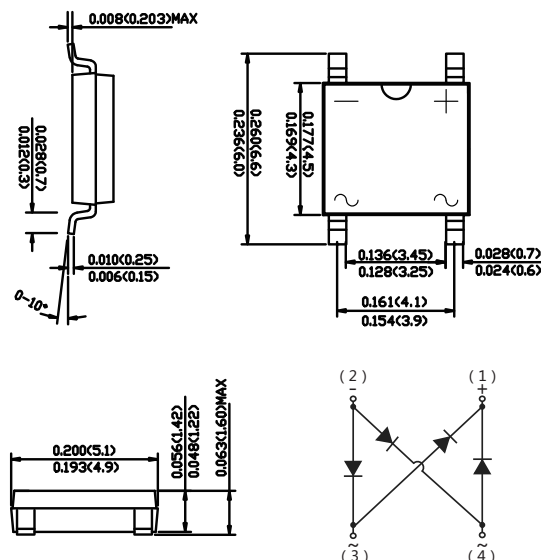




Voltage Range - 200 to 1000 V olts Current - 1.0 Ampere

Features

- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260°/10 seconds at 5 lbs., (2.3kg) tension
- ◆ Small size, simple installation
- ◆ High surge current capability
- ◆ Glass passivated chip junction



Dimensions in inches and (millimeters)

Mechanical Data

Weight : 0.003 ounce, 0.098 grams

Maximum Ratings And Electrical Characteristics

Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	ABS2	ABS4	ABS6	ABS8	ABS10	UNITS
Marking Code		MDD ABS2	MDD ABS4	MDD ABS6	MDD ABS8	MDD ABS10	
Maximum repetitive peak reverse voltage	V _{RRM}	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	200	400	600	800	1000	V
Maximum average forward rectified current On glass-epoxy P.C.B.(Note1) On aluminum substrate(Note2)	I _{F(AV)}	0.8 1.0					A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30					A
Maximum instantaneous forward voltage drop per leg at 1A	V _F	0.95					V
Maximum DC reverse current T _A =25℃ at rated DC blocking voltage T _A =100℃	I _R	5 100					uA uA
Typical thermal resistance	R _{θJL} R _{θJA}	25 80					℃/W
Operating temperature range	T _J	-55 to +150					℃
storage temperature range	T _{STG}	-55 to +150					℃

2. On aluminum substrate P.C.B. with on area of 0.8"x0.8" (20x20mm) mounted on 0.05X0.05" (1.3X1.3mm) solder pad
3. Thermal resistance from junction to ambient and junction to lead mounted on P.C.B. with 0.2X0.2" (5X5mm) copper pads.



Ratings And Characteristic Curves

FIG.1 TYPICAL FORWARD CHARACTERISTICS

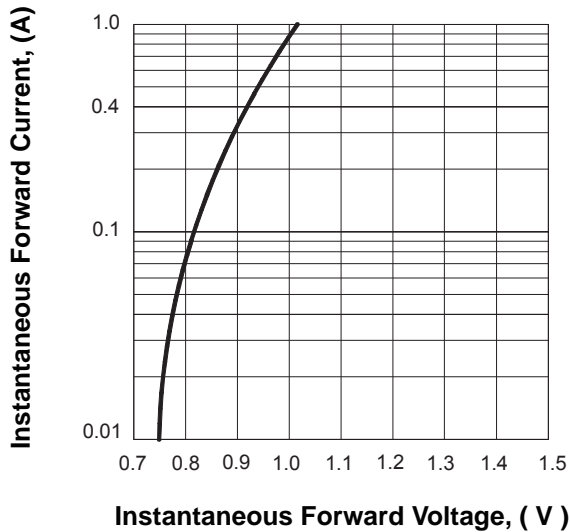


FIG.2 FORWARD DERATING CURVE

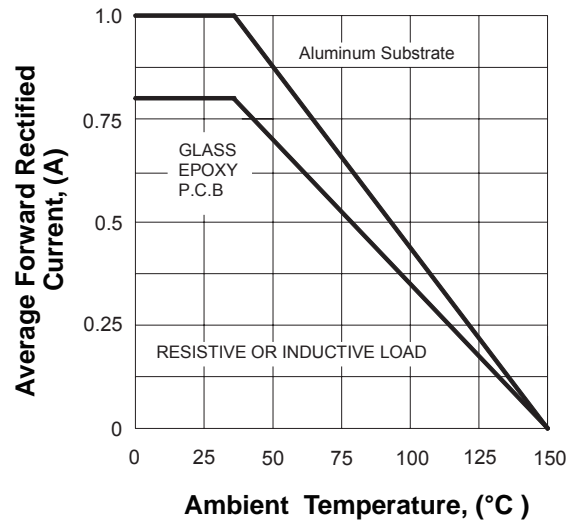


FIG.3 TYPICAL REVERSE CHARACTERISTICS

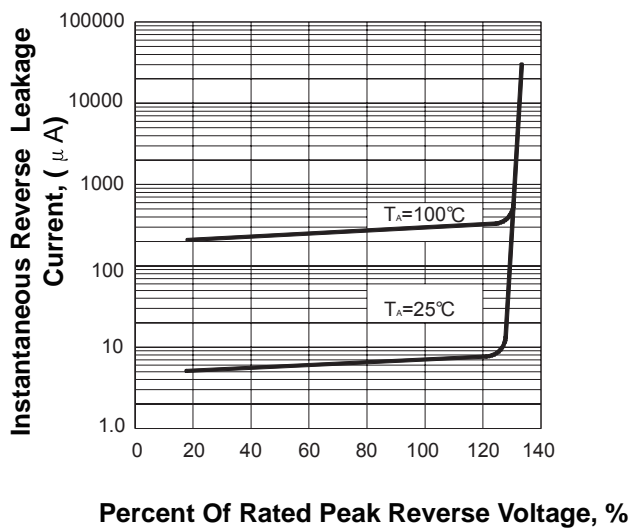
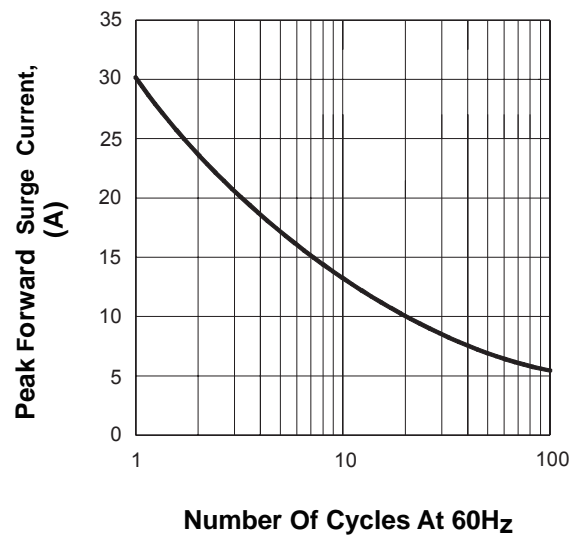


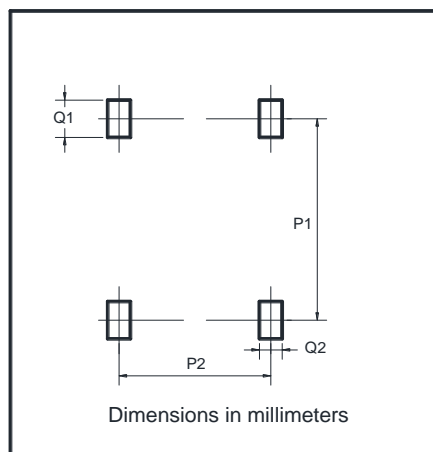
FIG.4 PEAK FORWARD SURGE CURRENT



The curve above is for reference only.



Suggested Pad Layout



Dim	Min
P1	5.72
P2	4.00
Q1	1.00
Q2	0.90

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